Tyrone Camarero Specifications

Camerero: SDI300A2TB-26

Key Feature

2U 4-Node BigTwin with 6 hot-swap 2.5" NVMe drives per node All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service; Application AcceleratorHigh-Performa nce File System, Diskless HPC Clusters Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:

- Dual Socket E2 (LGA-4710), Intel® Xeon® 6 6700 series processors with E-cores Note: Supports up to 205W TDP CPUs (Air Cooled)*, Supports up to 330W TDP CPUs (Liquid Cooled)
- *Air Cooled CPUs with TDP over 205W only supported under specific conditions. Contact a Tyrone representative for details."
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC
- · Flexible networking with OCP 3.0 AIOM slot
- "Up to 2 PCle 5.0 x16 LP slots, Internal PCle 5.0 for 2x NVMe M.2 support onboard
- Optional 4x NVMe M.2 support onboard with built-in HW RAID1 via SCC-A2NM2241GH-B1"
- "Up to 6 front hot-swap 2.5"" PCIe 5.0 NVMe drive bays, M.2
- 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); VROC required for RAID)"
- "Fans: 4x 16K RPM Counter Rotating 80x80x56mm Fan(s)
- · Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)"
- 2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies







Processor/Cache

"Dual Socket E2 (LGA-4710), Intel® Xeon® 6 Processor

6700 series processors with E-cores Note: Supports up to 205W TDP CPUs (Air Cooled)*, Supports up to 330W TDP CPUs

(Liquid Cooled)

*Air Cooled CPUs with TDP over 205W only supported under specific conditions. Contact

a Tyrone representative for details."

Chipset

Chipset System on Chip

System Memory

16 DIMM slots, Max Memory (1DPC): Up to Memory Capacity 4TB 6400MT/s ECC DDR5 RDIMM

Expansion Slot

2 PCle 5.0 x16 LP slots, 1 PCle 5.0 x16 AIOM **PCI-Express**

slot (OCP 3.0 compatible)

Integrated Onboard

1 RJ45 1 GbE Dedicated BMC LAN port(s) LAN **USB** 2 USB 3.0 Gen2 Type-A port(s) (Rear)

Add-on Options

Raid Card None

Optical Drive

None

Drive bays

HDD Bays 6 front hot-swap 2.5"" PCIe 5.0 NVMe

drive bays,

M.2: 2 M.2 PCle 5.0 x4 NVMe slots (M-key 22110(default); VROC required

for RAID)"

Power Supply

2x 3600W Redundant (1 + 1) Titanium **Power Supply**

Level (96%) power supplies

Cooling System

Fans 4x 16K RPM Counter Rotating

80x80x56mm Fan(s)

Liquid Cooling Direct to Chip (D2C) Cold Plate (optional)

Form Factor

2U Rackmount Form Factor

Dimensions

Dimensions 3.47" (88 mm), Width: 17.68" (449 mm),

Depth: 28.75" (730 mm)

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